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stack \$4 ad) (metal ad) (substrate base carrier))			
<p>Aug 2004</p>			

	U	I	Inventor	Document#	Issue	P	Title	Current	Current XBRL Retrieval	S	C	P	A	Image Doc.	P
1			Taneda, Taka	US 2004008	2004.0		Laminated film and method forming film	428/615-427/248.1		R	F	F	F	F	US 2004008
2			Asami, Hiroshi	US 2004000	2004.0	2	Method of manufacturing multilayer wiring s	28/830-174/258;		F	F	F	F	F	US 2004000
3			Miyano, Yos	US 2002010	2002.0	9	Electric contact and electronic device	439/888;		R	C	C	F	F	US 2002010
4			Park, Se-Chul	US 2002010	2002.0	1	Ag-pre-plated lead frame for semiconductor p	174/255-257/E23.05		R	F	F	F	F	US 2002010
5			Park, Se-Chul	US 6518508	2003.0	1	Ag-pre-plated lead frame for semiconductor p	174/255; 174/256;		R	F	F	F	F	US 6518508
6			Lee, Kyu-han	US 6469386	2002.1		Lead frame and method for plating the same	257/748; 257/666;		R	F	F	F	F	US 6469386
7			Lee, Kyu-han	US 6232651	2001.0	9	Lead frame for semiconductor device	257/666; 257/736;		R	F	F	F	F	US 6232651
8			Takada, Akiy	US 6210825	2001.0	9	Safety valve element for battery and battery	429/58-429/53		R	F	F	F	F	US 6210825
9			Park, Se-chul	US 6150713	2000.1	1	Lead frame for semiconductor package and l	257/677-257/782;		F	F	F	F	F	US 6150713
10			Saijo, Kijei et	US 6150037	2000.1	8	Cladding material	428/615-137/68.23;		R	C	C	F	F	US 6150037